

Title (en)  
SIM CARD AND MANUFACTURING METHOD

Title (de)  
SIM-KARTE UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)  
CARTE SIM ET PROCÉDÉ DE FABRICATION

Publication  
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Application  
**EP 11837644 A 20111004**

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Abstract (en)  
[origin: WO2012059813A2] The present invention provides a method for manufacturing a SIM card without using a carrier card. An array of conductive modules is formed onto a first surface of a substrate. These conductive modules are spaced apart from each other with spacing configured to provide peripheral portions surrounding each conductive module. The peripheral portions are sized to provide sufficient substrate parts to form the SIM card body based on the industry standard. The substrate is then trimmed to form SIM card bodies and an IC chip is bonded to a second side of the substrate. The IC chip is then encapsulated and thereafter, a molding process is carried out to supply and form a molding part to cover the encapsulated IC chip and also flatten the bottom side of the substrate. The molding part together with the substrate forms a SIM card with the thickness conforming to the industry standard.

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